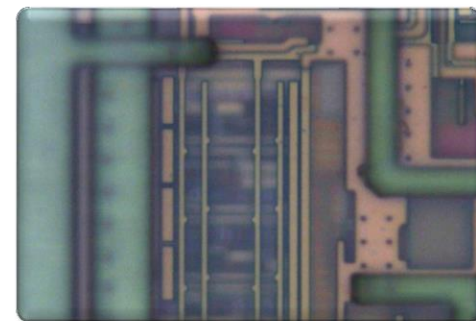
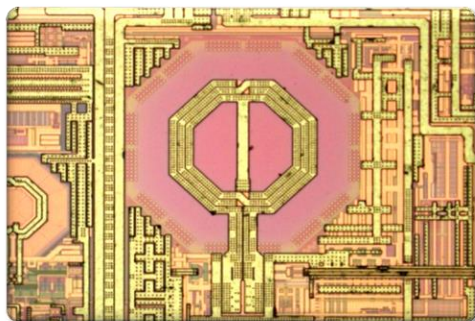




ESP8089

Wi-Fi Module IC



Product Analysis Report

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ESP8089 Product Analysis Report

Table Of Contents

Product Analysis

Device Summary.....	Page 2
Package Overview	Page 3
Die Photo.....	Page 5
Die Mark.....	Page 6
Die Corner.....	Page 7
Pad Size.....	Page 8
Sample Images.....	Page 9
General Structure.....	Page 10
Major Findings	Page16

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